



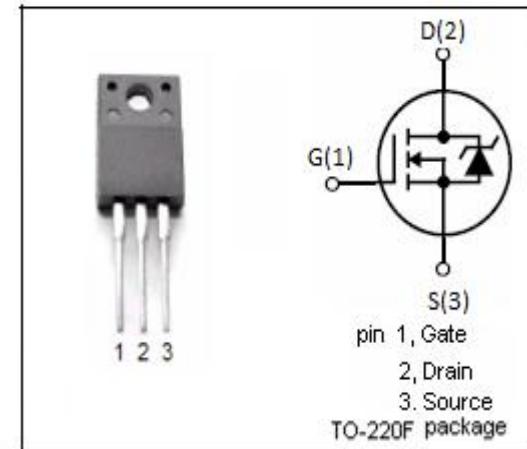
INCHANGE Semiconductor

isc N-Channel MOSFET Transistor

SPA11N80C3

• FEATURES

- New revolutionary high voltage technology
- Ultra low gate charge
- High peak current capability
- Improved transconductance
- 100% avalanche tested
- Minimum Lot-to-Lot variations for robust device performance and reliable operation



• APPLICATIONS

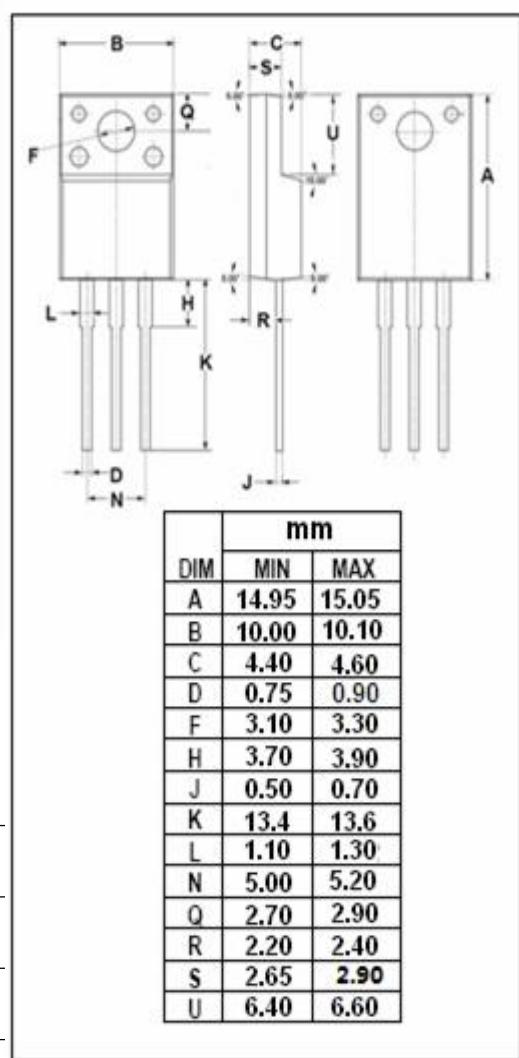
- Switching applications

• ABSOLUTE MAXIMUM RATINGS($T_a=25^\circ\text{C}$)

SYMBOL	PARAMETER	VALUE	UNIT
V_{DSS}	Drain-Source Voltage	800	V
V_{GSS}	Gate-Source Voltage	± 20	V
I_D	Drain Current-Continuous@ $T_c=25^\circ\text{C}$ $T_c=100^\circ\text{C}$	11 7.1	A
I_{DM}	Drain Current-Single Pulsed	33	A
P_D	Total Dissipation	41	W
T_j	Operating Junction Temperature	-55~150	°C
T_{stg}	Storage Temperature	-55~150	°C

• THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	MAX	UNIT
$R_{th(ch-c)}$	Channel-to-case thermal resistance	3.7	°C/W
$R_{th(ch-a)}$	Channel-to-ambient thermal resistance	62	°C/W





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ELECTRICAL CHARACTERISTICS

 $T_c=25^\circ\text{C}$ unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
BV_{DSS}	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}; \text{I}_D= 0.25\text{mA}$	800			V
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	$\text{V}_{\text{DS}}=\pm 20\text{V}; \text{I}_D=0.68\text{mA}$	2.1		3.9	V
$\text{R}_{\text{DS(on)}}$	Drain-Source On-Resistance	$\text{V}_{\text{GS}}= 10\text{V}; \text{I}_D=7.1\text{A}$		390	450	$\text{m}\Omega$
I_{GSS}	Gate-Source Leakage Current	$\text{V}_{\text{GS}}= \pm 20\text{V}; \text{V}_{\text{DS}}= 0\text{V}$			± 0.1	μA
I_{DSS}	Drain-Source Leakage Current	$\text{V}_{\text{DS}}= 800\text{V}; \text{V}_{\text{GS}}= 0\text{V}; \text{T}_J=25^\circ\text{C}$ $\text{T}_J=125^\circ\text{C}$			20 200	μA
V_{SDF}	Diode forward voltage	$\text{I}_{\text{SD}}=11\text{A}, \text{V}_{\text{GS}} = 0 \text{ V}$			1.2	V